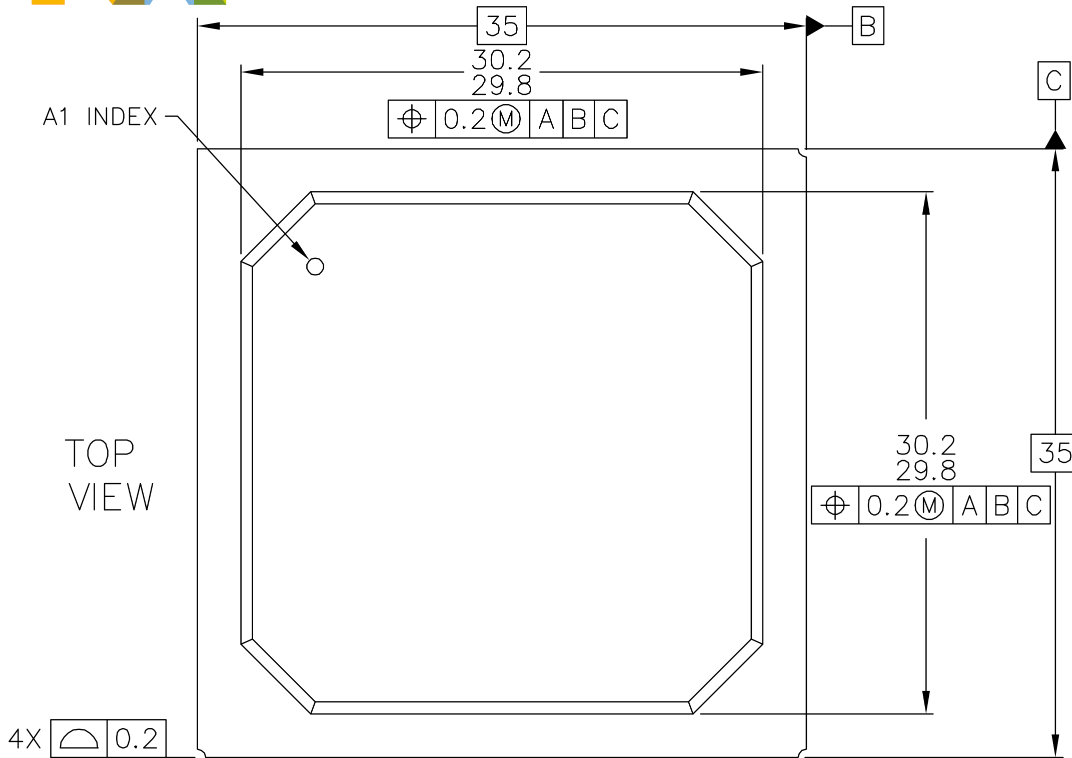

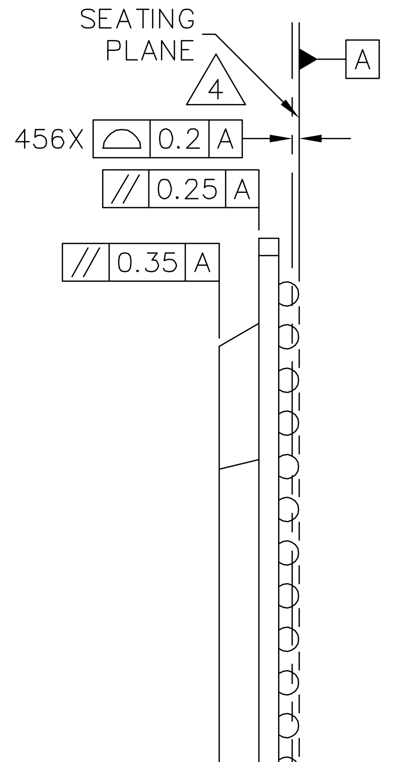

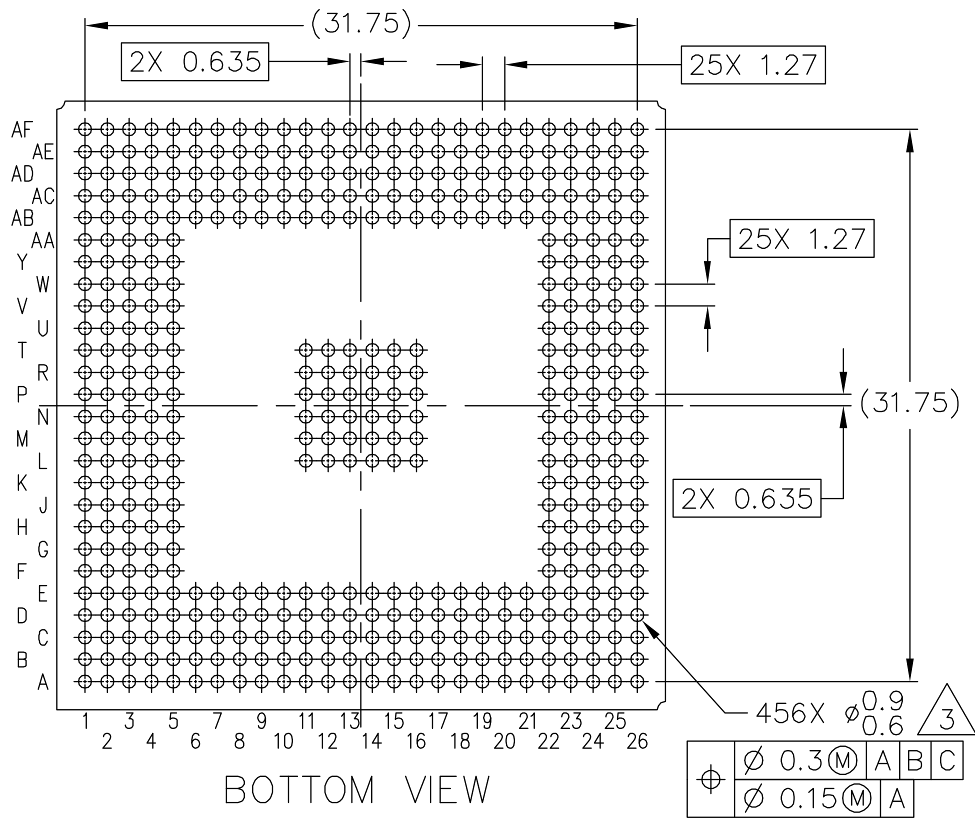

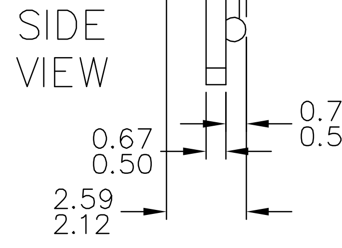

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MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 456 I/O PBGA 35 X 35 PKG, 1.27 MM PITCH	DOCUMENT NO: 98ARS10501D REV: B
	STANDARD: JEDEC MS-034 BAR-2
	SOT1634-1 03 MAR 2016

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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	SOT1634-1	03 MAR 2016